

**Amendments to the Claims**

The current listing of the claims replaces all previous amendments and listings of the claims.

1. (Currently Amended) An electronic component comprising:

a semiconductor device comprising first lands electrically connected to second lands of a board, said second lands connected to wires ~~of a board~~,

wherein at least one of the second lands comprises a primary land and an auxiliary land, the at least one second land connecting to at least one of the wires where a predetermined tensile stress is configured to be applied between said at least one second land and said at least one wire,

the primary land comprises an arcuate shape, and

the auxiliary land comprises a first portion disposed adjacent the primary land and a second portion connecting to the at least one wire, the first portion having a greater cross sectional area than the second portion, and

wherein the at least one wire comprises a via land, the via land including an arcuate portion electrically connected to a via hole.

2. (Previously Presented) The electronic component according to claim 1, wherein said auxiliary land is configured to be disposed where the predetermined tensile stress is applied when a load is applied to said board.

3. (Currently Amended) The electronic component according to claim 2, wherein said auxiliary land electrically connects with at least one of the first lands at a corner of the semiconductor device.

4. (Currently Amended) The electronic component according to claim 2, wherein said auxiliary land electrically connects with at least one of the first lands at an end of an integrated circuit of the semiconductor device.

5. (Previously Presented) The electronic component according to claim 2, wherein said auxiliary land is configured to be disposed so as to extend in a direction in which a warpage of said board is generated.

6. (Currently Amended) The electronic component according to claim 2, wherein said auxiliary land is configured to be disposed where the predetermined tensile stress is applied during correction of a distortion of said board during an assembly of the semiconductor device to the board.

7. (Previously Presented) The electronic component according to claim 2, wherein said auxiliary land comprises a third portion disposed between the first and second portions, the third portion having a cross sectional area less than the first portion and greater than the second portion.

8. (Currently Amended) The electronic component according to claim 3, wherein said auxiliary land has a shape determined based on a position of the auxiliary land in relation to a corner of the semiconductor device.

9. (Previously Presented) The electronic component according to claim 3, wherein said auxiliary land comprises an arcuate shape.

10. (Previously Presented) The electronic component according to claim 2, wherein the at least one second land comprises a second auxiliary land disposed adjacent a through hole.

11.-15. (Canceled)

16. (Currently Amended) An electronic component comprising:  
a semiconductor device comprising first lands electrically connected to second lands of a printed circuit board, said second lands connected to wires ~~of a board~~,

wherein at least one of the second lands comprises a primary land and an auxiliary land, the at least one second land connecting to at least one of the wires where a

predetermined tensile stress is configured to be applied between the at least one second land and the at least one wire,

the primary land comprises an arcuate shape, and

the auxiliary land comprises a first portion disposed adjacent the primary land and a second portion connecting to the at least one wire, the first portion having a greater cross sectional area than the second portion, and

wherein the at least one wire comprises a via land, the via land including an arcuate portion electrically connected to a via hole.

17. (Currently Amended) An electronic component, comprising:

a semiconductor device comprising ~~first and second~~ at least one semiconductor ~~lands~~ land;

a board comprising ~~first and second~~ at least one board ~~lands~~ land electrically connected to the ~~first and second~~ at least one semiconductor ~~lands~~ land, the ~~first~~ at least one board land including a primary portion contacting the ~~first~~ at least one semiconductor land and an auxiliary portion ~~configured to electrically connect~~ connected to a wire,

wherein the primary portion comprises an arcuate shape, and

the auxiliary portion comprises a first portion electrically connected to the primary portion and a second portion ~~configured to contact~~ electrically connected to the wire, the first portion having a greater cross sectional area than the second portion, and

wherein the wire comprises a via land, the via land including an arcuate portion electrically connected to a via hole.

18. (Previously Presented) The electronic component according to claim 17, wherein the primary portion comprises a circular shape.

19. (Previously Presented) The electronic component according to claim 17, wherein the auxiliary portion has an about triangular shape.

20. (Previously Presented) The electronic component according to claim 17, wherein the auxiliary portion has a tapered shape.

21. (Previously Presented) The electronic component according to claim 17, wherein the auxiliary portion has a tear drop shape.

22. (Currently Amended) The electronic component according to claim 17, wherein the auxiliary portion has a third portion between the first and second portions, the third portion having a cross sectional area between ~~values~~ of the cross sectional areas of the first and second portions.